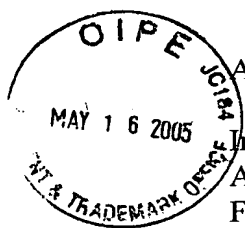


IPW



Attorney Docket No. 9180-29

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Krishna K. Nair et al;

Application No.: 10/601,938

Group Art Unit: 2824

Filed: June 23, 2003

Examiner: Douglas M. Menz

For: METHODS OF FORMING ELECTRONIC STRUCTURES INCLUDING  
CONDUCTIVE SHUNT LAYERS AND RELATED STRUCTURES

Date: May 12, 2005

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

**INFORMATION DISCLOSURE STATEMENT**

**PURSUANT TO 37 C.F.R. §1.97(c)**

Sir:

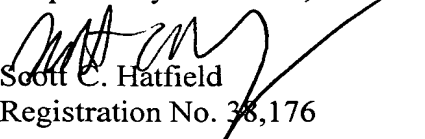
Attached is a list of documents on Form PTO-1449, together with a copy of any listed foreign patent document and/or non-patent literature. A copy of any listed U.S. patent and/or U.S. patent application publication is not provided herewith in accordance with the amendment by the U.S. Patent and Trademark Office to 37 C.F.R. § 1.98(a)(2)(ii) effective October 21, 2004.

This Information Disclosure Statement is submitted in accordance with 37 C.F.R. § 1.97(c), before final Office Action or Allowance, whichever is earlier.

In accordance with the requirements of 37 C.F.R. § 1.97(c)(2), a check for the \$180.00 fee specified in 37 C.F.R. § 1.17(p) is enclosed. This amount is believed to be correct. However, the Commissioner is authorized to charge any deficiency or credit any overpayment to Deposit Account No. 50-0220.

It is requested that these documents be considered by the Examiner and officially made of record in accordance with the provisions of 37 C.F.R. §1.56 and Section 609 of the MPEP.

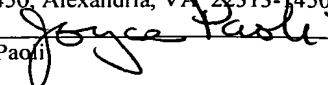
Respectfully submitted,

  
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**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Sheet

1

of 5

A4

**Complete if Known**

Application Number	10/601,938
Filing Date	June 23, 2003
First Named Inventor	Krishna K. Nair
Group Art Unit	2829
Examiner Name	Douglas M. Menz
Attorney Docket Number	9180-29

**U.S. PATENTS AND PATENT PUBLICATIONS**

Examiner Initials*	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Number	Kind Code (if known)		
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	2.	US-3,105,869		Branch et al;	10/1963
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Examiner Signature

Date Considered

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Substitute form 1449A/PTO  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)				<b>Complete if Known</b>	
				Application Number	10/601,938
				Filing Date	June 23, 2003
				First Named Inventor	Krishna K. Nair
				Group Art Unit	2829
				Examiner Name	Douglas M. Menz
Sheet	2	of 5	A4	Attorney Docket Number	9180-29

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Examiner Signature		Date Considered	
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Substitute form 1449A/PTO			<b>Complete if Known</b>		
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			Filing Date	June 23, 2003	
			First Named Inventor	Krishna K. Nair	
			Group Art Unit	2829	
			Examiner Name	Douglas M. Menz	
Sheet	3	of 5	A4	Attorney Docket Number	9180-29

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Examiner Initials*	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	T
		Office	Number	Kind Code (if known)			
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				Group Art Unit	2829
				Examiner Name	Douglas M. Menz
Sheet	4	of 5	A4	Attorney Docket Number	9180-29

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#### OTHER NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T
	181.	Howell et al; "Area Array Solder Interconnection Technology for the Three-Dimensional Silicon Cube", Proceedings of the 1995 45 <sup>th</sup> Electronic Components & Technology Conference, pp 1174-1178.	
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	185.	Guckel et al., <i>Electromagnetic Linear Actuators with Inductive Position Sensing for Micro Relay, Micro Valve and Precision Positioning Applications</i> , Transducers '95, Eurosensors IX, The 8 <sup>th</sup> International Conference on Solid-State Sensors and Actuators, and Eurosensors IX, pp 324-327.	
	186.	Hashimoto et al; <i>Thermally Controlled Magnetization Microrelay</i> , Transducers '95, Eurosensors IX, The 8 <sup>th</sup> International Conference on Solid-State Sensors and Actuators, and Eurosensors IX, pp 361-364.	
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Examiner Signature		Date Considered	
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				Filing Date	June 23, 2003
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				Group Art Unit	2829
				Examiner Name	Douglas M. Menz
Sheet	5	of 5	A4	Attorney Docket Number	9180-29

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